



## QUAD/DUAL N-CHANNEL ENHANCEMENT MODE EPAD® MATCHED PAIR MOSFET ARRAY

#### $V_{GS(th)} = +1.4V$

#### **GENERAL DESCRIPTION**

ALD110814/ALD110914 are monolithic quad/dual N-Channel MOSFETs matched at the factory using ALD's proven EPAD® CMOS technology. These devices are intended for low voltage, small signal applications.

The ALD110814/ALD110914 MOSFETs are designed and built with exceptional device electrical characteristics matching. Since these devices are on the same monolithic chip, they also exhibit excellent tempco tracking characteristics. Each device is versatile as a circuit element and is a useful design component for a broad range of analog applications. They are basic building blocks for current sources, differential amplifier input stages, transmission gates, and multiplexer applications. For most applications, connect V- and N/C pins to the most negative voltage potential in the system and V+ pin to the most positive voltage potential (or left open unused). All other pins must have voltages within these voltage limits.

The ALD110814/ALD110914 devices are built for minimum offset voltage and differential thermal response, and they are designed for switching and amplifying applications in +1.5V to +10V systems where low input bias current, low input capacitance and fast switching speed are desired. Since these are MOSFET devices, they feature very large (almost infinite) current gain in a low frequency, or near DC, operating environment.

The ALD110814/ALD110914 are suitable for use in precision applications which require very high current gain, beta, such as current mirrors and current sources. The high input impedance and the high DC current gain of the Field Effect Transistors result in extremely low current loss through the control gate. The DC current gain is limited by the gate input leakage current, which is specified at 30pA at room temperature. For example, DC beta of the device at a drain current of 3mA and input leakage current of 30pA at 25°C is = 3mA/30pA = 100,000,000.

#### **FEATURES**

- Enhancement-mode (normally off)
- Standard Gate Threshold Voltages: +1.4V
- Matched MOSFET to MOSFET characteristics
- Tight lot to lot parametric control
- Parallel connection of MOSFETs to increase drain currents
- Low input capacitance
- VGS(th) match to 10mV
- High input impedance  $10^{12}\Omega$  typical
- · Positive, zero, and negative VGS(th) temperature coefficient
- DC current gain >10<sup>8</sup>
- · Low input and output leakage currents

#### **ORDERING INFORMATION**

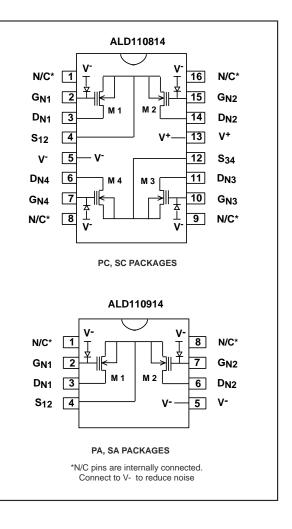
0°C to +	Operating Temp 70°C	erature Range* 0°C to +70°C		
16-Pin Plastic Dip Package	Plastic Dip SOIC		8Pin SOIC Package	
ALD110814PC	ALD110814SC	ALD110914PA	ALD110914SA	

\* Contact factory for industrial or military temp. ranges or user-specified threshold voltage values.

#### APPLICATIONS

- Precision current mirrors
- Precision current sources
- Voltage choppers
- Differential amplifier input stages
- Discrete voltage comparators
- Voltage bias circuits
- Sample and Hold circuits
- Analog inverters
- Level shifters
- · Source followers and buffers
- Current multipliers
- Discrete analog multiplexers/matrices
- Discrete analog switches

### PIN CONFIGURATION



Rev 1.0-0506 ©2 005 Advanced Linear Devices, Inc. 415 Tasman Drive, Sunnyvale, California 94089-1706 Tel: (408) 747-1155 Fax: (408) 747-1286 www.aldinc.com

## ABSOLUTE MAXIMUM RATINGS

Drain-Source voltage, V <sub>DS</sub>	10.6V
Gate-Source voltage, V <sub>GS</sub>	10.6V
Power dissipation	500 mW
Operating temperature range PA, SA, PC, SC package	0°C to +70°C
Storage temperature range	65°C to +150°C
Lead temperature, 10 seconds	+260°C

## OPERATING ELECTRICAL CHARACTERISTICS

# V+ = +5V (or open) V- = GND TA = $25^{\circ}$ C unless otherwise specified

CAUTION: ESD Sensitive Device. Use static control procedures in ESD controlled environment.

Parameter	Symbol	ALD110814 / ALD110914				
		Min	Тур	Мах	Unit	Test Conditions
Gate Threshold Voltage	VGS(th)	1.38	1.40	1.42	V	I <sub>DS</sub> =1μA V <sub>DS</sub> = 0.1V
Offset Voltage VGS(th)1-VGS(th)2	VOS		3	10	mV	I <sub>DS</sub> =1µA
Offset VoltageTempco	TC AVOS		5		μV/ °C	VDS1 = VDS2
GateThreshold Voltage Tempco	TC∆VGS(th)		-1.7 0.0 +1.6		mV °C	$I_D = 1\mu A$ $I_D = 20\mu A, V_{DS} = 0.1V$ $I_D = 40\mu A$
On Drain Current	IDS (ON)		12.0 3.0		mA	VGS = +10.6V VGS = +5.4V VDS = +5V
Forward Transconductance	GFS		1.4		mmho	VGS = +5.4V V <sub>DS</sub> = +10.4V
Transconductance Mismatch	∆GFS		1.8		%	
Output Conductance	GOS		68		μmho	VGS = + 5.4V VDS = +10.4V
Drain Source On Resistance	R <sub>DS</sub> (ON)		500		Ω	V <sub>DS</sub> = 0.1V V <sub>GS</sub> = +4.0V
Drain Source On Resistance Mismatch	∆RDS (ON)		0.5		%	VDS = 0.1V VGS = +5.4V
Drain Source Breakdown Voltage	BV <sub>DSX</sub>	10			V	IDS = 1.0μA VGS = -0.4V
Drain Source Leakage Current <sup>1</sup>	IDS (OFF)		10	100 4	pA nA	V <sub>GS</sub> = +0.4V V <sub>DS</sub> =10V, T <sub>A</sub> = 125°C
Gate Leakage Current <sup>1</sup>	IGSS		3	30 1	pA nA	V <sub>DS</sub> = 0V V <sub>GS</sub> = 10V T <sub>A</sub> =125°C
Input Capacitance	CISS		2.5		pF	
Transfer Reverse Capacitance	CRSS		0.1		pF	
Turn-on Delay Time	t <sub>on</sub>		10		ns	$V^+ = 5V R_L = 5K\Omega$
Turn-off Delay Time	toff		10		ns	$V^+ = 5V R_L = 5K\Omega$
Crosstalk			60		dB	f = 100KHz

Notes: <sup>1</sup> Consists of junction leakage currents